

## N-channel 600 V, 0.260 $\Omega$ typ., 12 A MDmesh™ DM2 Power MOSFET in a TO-247 package

Datasheet - production data

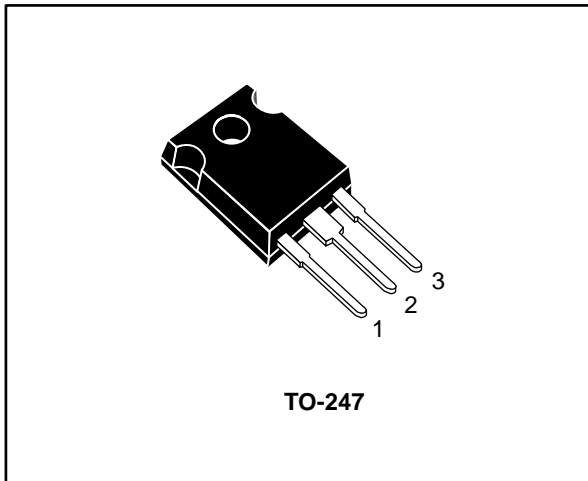
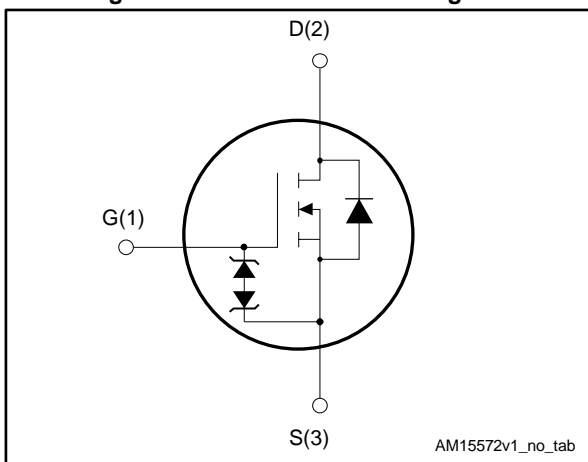


Figure 1: Internal schematic diagram



### Features

Order code	V <sub>DS</sub>	R <sub>DS(on)</sub> max.	I <sub>D</sub>
STW18N60DM2	600 V	0.295 $\Omega$	12 A

- Fast-recovery body diode
- Extremely low gate charge and input capacitance
- Low on-resistance
- 100% avalanche tested
- Extremely high dv/dt ruggedness
- Zener-protected

### Applications

- Switching applications

### Description

This high voltage N-channel Power MOSFET is part of the MDmesh™ DM2 fast recovery diode series. It offers very low recovery charge ( $Q_{rr}$ ) and time ( $t_{rr}$ ) combined with low  $R_{DS(on)}$ , rendering it suitable for the most demanding high efficiency converters and ideal for bridge topologies and ZVS phase-shift converters.

Table 1: Device summary

Order code	Marking	Package	Packing
STW18N60DM2	18N60DM2	TO-247	Tube

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# 1 Electrical ratings

**Table 2: Absolute maximum ratings**

Symbol	Parameter	Value	Unit
$V_{GS}$	Gate-source voltage	$\pm 25$	V
$I_D$	Drain current (continuous) at $T_{case} = 25\text{ °C}$	12	A
	Drain current (continuous) at $T_{case} = 100\text{ °C}$	7.6	
$I_{DM}^{(1)}$	Drain current (pulsed)	48	A
$P_{TOT}$	Total dissipation at $T_{case} = 25\text{ °C}$	90	W
$dv/dt^{(2)}$	Peak diode recovery voltage slope	40	V/ns
$dv/dt^{(3)}$	MOSFET $dv/dt$ ruggedness	50	
$T_{stg}$	Storage temperature	-55 to 150	°C
$T_j$	Maximum junction temperature	150	

**Notes:**

- (1) Pulse width is limited by safe operating area.  
 (2)  $I_{SD} \leq 12\text{ A}$ ,  $di/dt \leq 400\text{ A}/\mu\text{s}$ ,  $V_{DS(peak)} < V_{(BR)DSS}$ ,  $V_{DD} = 80\% V_{(BR)DSS}$ .  
 (3)  $V_{DS} \leq 480\text{ V}$ .

**Table 3: Thermal data**

Symbol	Parameter	Value	Unit
$R_{thj-case}$	Thermal resistance junction-case	1.39	°C/W
$R_{thj-amb}$	Thermal resistance junction-ambient	50	

**Table 4: Avalanche characteristics**

Symbol	Parameter	Value	Unit
$I_{AR}^{(1)}$	Avalanche current, repetitive or not repetitive	2.5	A
$E_{AR}^{(2)}$	Single pulse avalanche energy	380	mJ

**Notes:**

- (1) Pulse width is limited by  $T_{jmax}$ .  
 (2) Starting  $T_j = 25\text{ °C}$ ,  $I_D = I_{AR}$ ,  $V_{DD} = 50\text{ V}$ .

## 2 Electrical characteristics

( $T_{\text{case}} = 25\text{ °C}$  unless otherwise specified)

**Table 5: Static**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{(\text{BR})\text{DSS}}$	Drain-source breakdown voltage	$V_{\text{GS}} = 0\text{ V}$ , $I_{\text{D}} = 1\text{ mA}$	600			V
$I_{\text{DSS}}$	Zero gate voltage drain current	$V_{\text{GS}} = 0\text{ V}$ , $V_{\text{DS}} = 600\text{ V}$			1.5	$\mu\text{A}$
		$V_{\text{GS}} = 0\text{ V}$ , $V_{\text{DS}} = 600\text{ V}$ , $T_{\text{case}} = 125\text{ °C}$			100	$\mu\text{A}$
$I_{\text{GSS}}$	Gate-body leakage current	$V_{\text{DS}} = 0\text{ V}$ , $V_{\text{GS}} = \pm 25\text{ V}$			$\pm 10$	$\mu\text{A}$
$V_{\text{GS(th)}}$	Gate threshold voltage	$V_{\text{DS}} = V_{\text{GS}}$ , $I_{\text{D}} = 250\text{ }\mu\text{A}$	3	4	5	V
$R_{\text{DS(on)}}$	Static drain-source on-resistance	$V_{\text{GS}} = 10\text{ V}$ , $I_{\text{D}} = 6\text{ A}$		0.260	0.295	$\Omega$

**Table 6: Dynamic**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$C_{\text{iss}}$	Input capacitance	$V_{\text{DS}} = 100\text{ V}$ , $f = 1\text{ MHz}$ , $V_{\text{GS}} = 0\text{ V}$	-	800	-	$\mu\text{F}$
$C_{\text{oss}}$	Output capacitance		-	40	-	
$C_{\text{riss}}$	Reverse transfer capacitance		-	1.33	-	
$C_{\text{oss eq.}}^{(1)}$	Equivalent output capacitance	$V_{\text{DS}} = 0\text{ to }480\text{ V}$ , $f = 1\text{ MHz}$ , $V_{\text{GS}} = 0\text{ V}$	-	80	-	$\mu\text{F}$
$R_{\text{G}}$	Intrinsic gate resistance	$f = 1\text{ MHz}$ , $I_{\text{D}} = 0\text{ A}$	-	5.6	-	$\mu\text{s}$
$Q_{\text{g}}$	Total gate charge	$V_{\text{DD}} = 480\text{ V}$ , $I_{\text{D}} = 12\text{ A}$ , $V_{\text{GS}} = 10\text{ V}$ (see <a href="#">Figure 14</a> : "Gate charge test circuit")	-	20	-	nC
$Q_{\text{gs}}$	Gate-source charge		-	5.2	-	
$Q_{\text{gd}}$	Gate-drain charge		-	8.5	-	

**Notes:**

<sup>(1)</sup>  $C_{\text{oss eq.}}$  is defined as a constant equivalent capacitance giving the same charging time as  $C_{\text{oss}}$  when  $V_{\text{DS}}$  increases from 0 to 80%  $V_{\text{DSS}}$

**Table 7: Switching times**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$t_{\text{d(on)}}$	Turn-on delay time	$V_{\text{DD}} = 300\text{ V}$ , $I_{\text{D}} = 6\text{ A}$ $R_{\text{G}} = 4.7\text{ }\Omega$ , $V_{\text{GS}} = 10\text{ V}$ (see <a href="#">Figure 13</a> : "Switching times test circuit for resistive load" and <a href="#">Figure 18</a> : "Switching time waveform")	-	13.5	-	ns
$t_{\text{r}}$	Rise time		-	8	-	
$t_{\text{d(off)}}$	Turn-off-delay time		-	9.5	-	
$t_{\text{f}}$	Fall time		-	32.5	-	

Table 8: Source-drain diode

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$I_{SD}$	Source-drain current		-		12	A
$I_{SDM}^{(1)}$	Source-drain current (pulsed)		-		48	A
$V_{SD}^{(2)}$	Forward on voltage	$V_{GS} = 0\text{ V}$ , $I_{SD} = 12\text{ A}$	-		1.6	V
$t_{rr}$	Reverse recovery time	$I_{SD} = 12\text{ A}$ , $di/dt = 100\text{ A}/\mu\text{s}$ , $V_{DD} = 60\text{ V}$ (see <i>Figure 15: "Test circuit for inductive load switching and diode recovery times"</i> )	-	125		ns
$Q_{rr}$	Reverse recovery charge		-	680		nC
$I_{RRM}$	Reverse recovery current		-	11		A
$t_{rr}$	Reverse recovery time	$I_{SD} = 12\text{ A}$ , $di/dt = 100\text{ A}/\mu\text{s}$ , $V_{DD} = 60\text{ V}$ , $T_j = 150\text{ °C}$ (see <i>Figure 15: "Test circuit for inductive load switching and diode recovery times"</i> )	-	190		ns
$Q_{rr}$	Reverse recovery charge		-	1200		nC
$I_{RRM}$	Reverse recovery current		-	13		A

**Notes:**

<sup>(1)</sup>Pulse width is limited by safe operating area.

<sup>(2)</sup>Pulse test: pulse duration = 300  $\mu\text{s}$ , duty cycle 1.5%.

## 2.1 Electrical characteristics (curves)

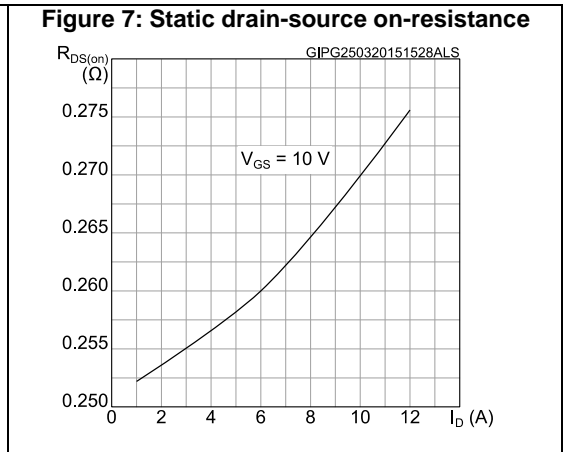
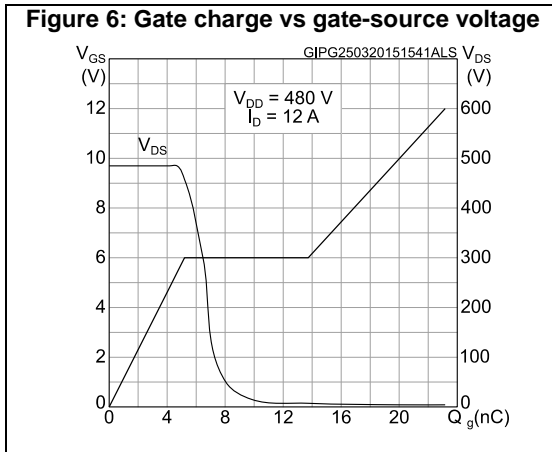
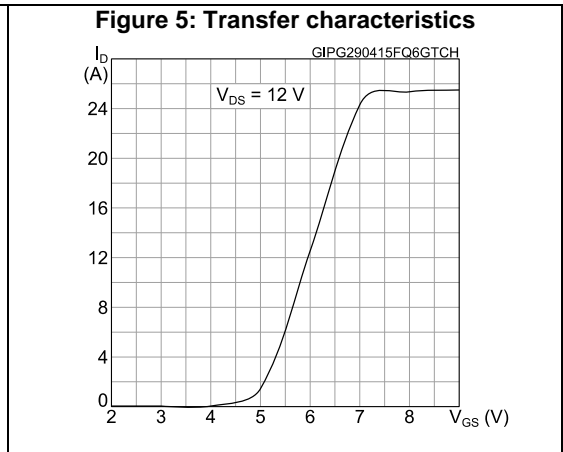
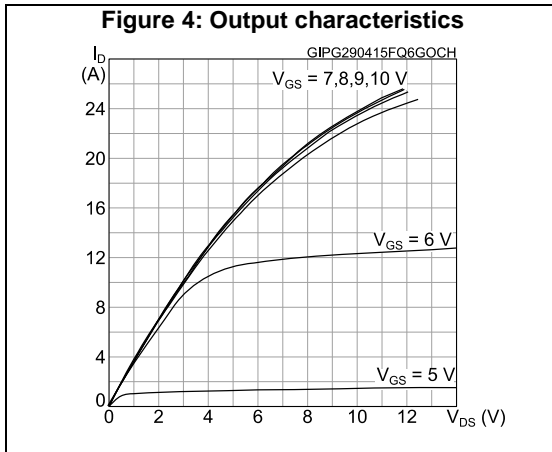
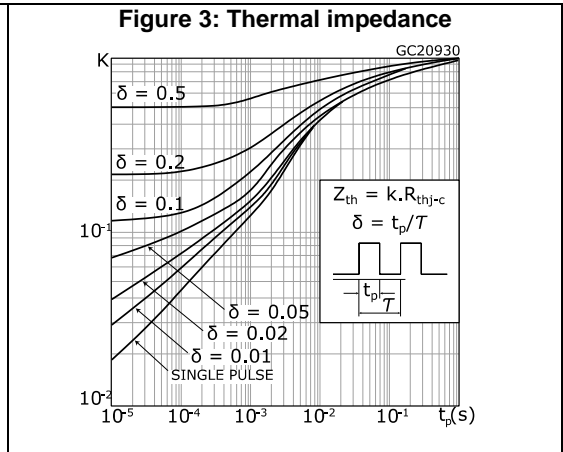
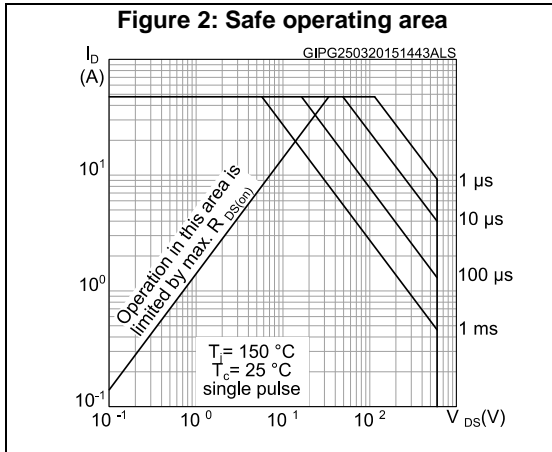


Figure 8: Capacitance variations

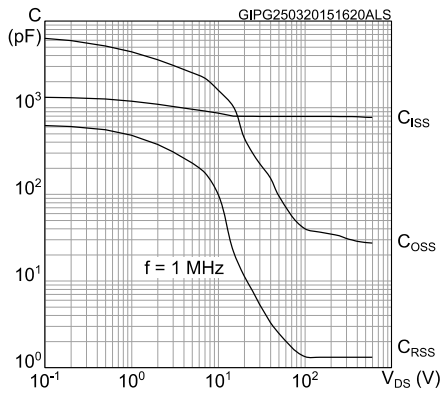


Figure 9: Normalized gate threshold voltage vs temperature

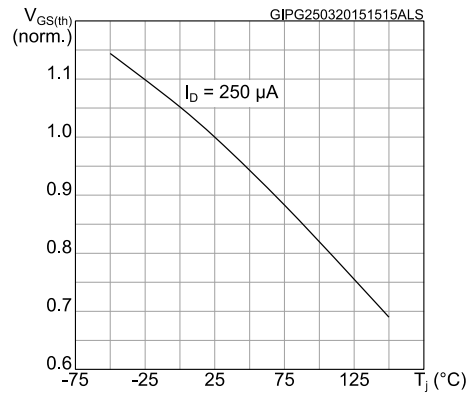


Figure 10: Normalized on-resistance vs temperature

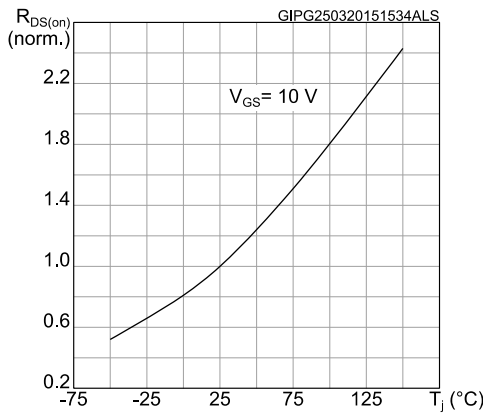


Figure 11: Normalized  $V_{(BR)DSS}$  vs temperature

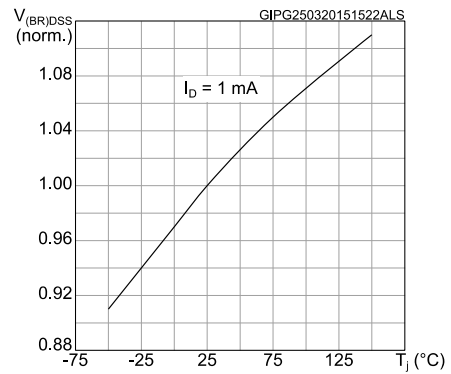
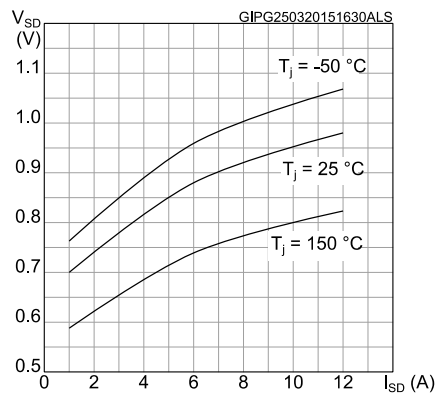
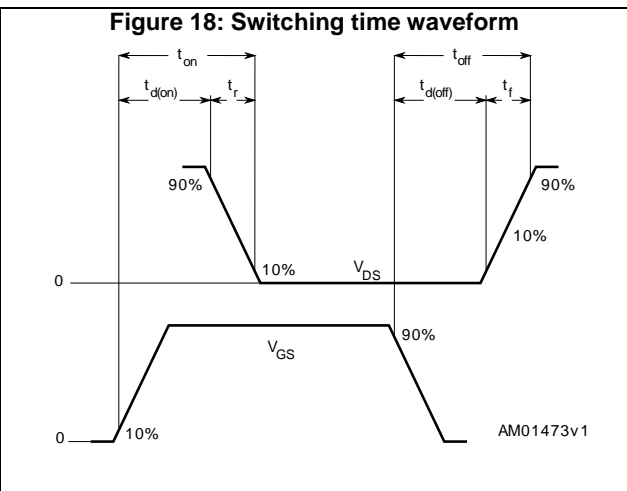
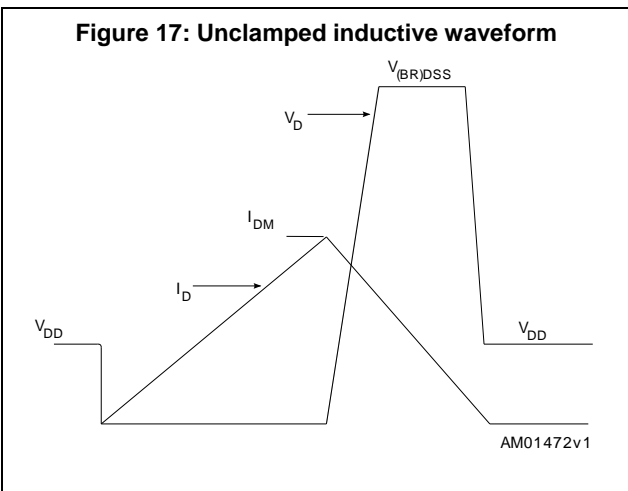
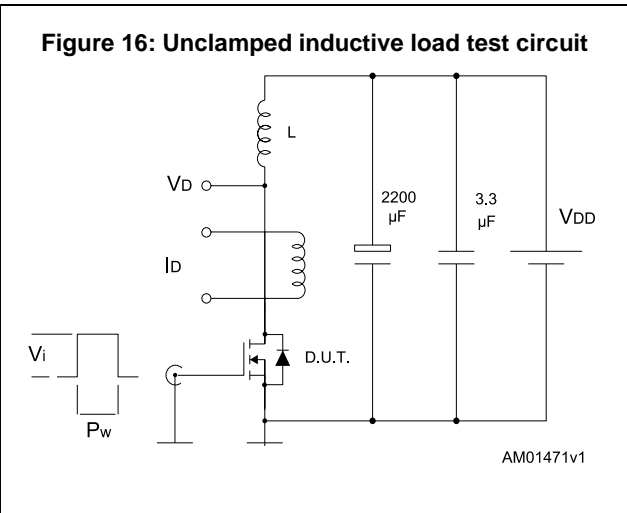
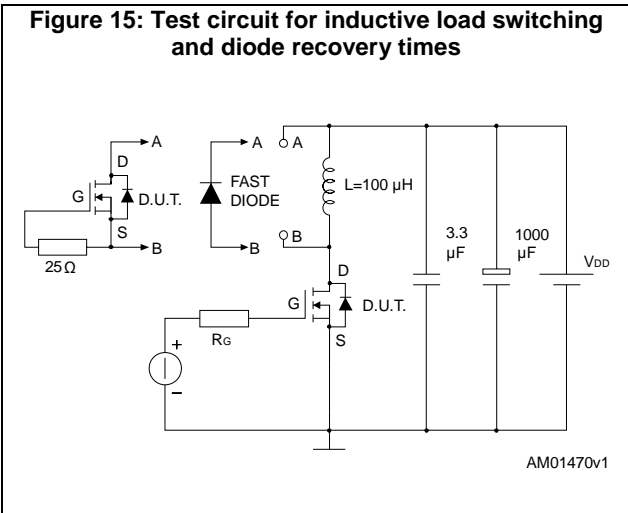
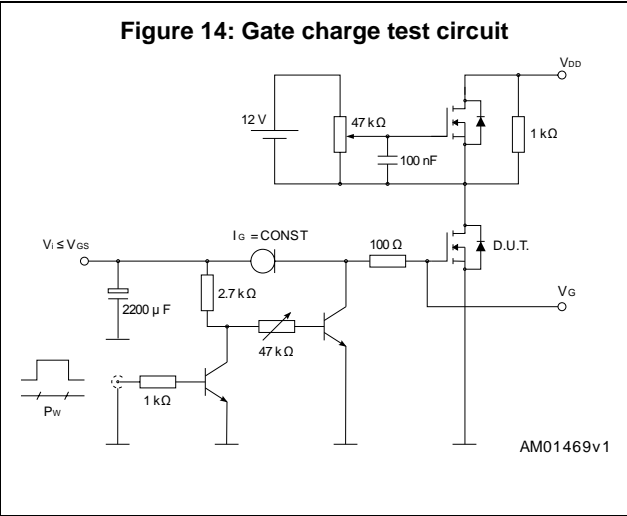
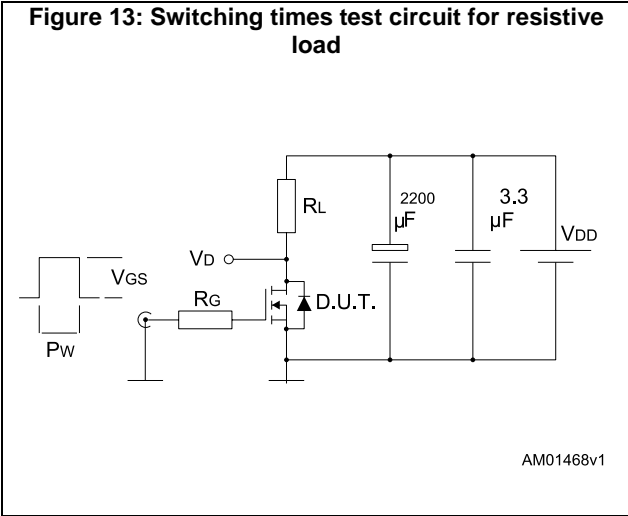


Figure 12: Source-drain diode forward characteristics



### 3 Test circuits





## 4 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: [www.st.com](http://www.st.com). ECOPACK® is an ST trademark.

### 4.1 TO-247 package information

Figure 19: TO-247 drawing

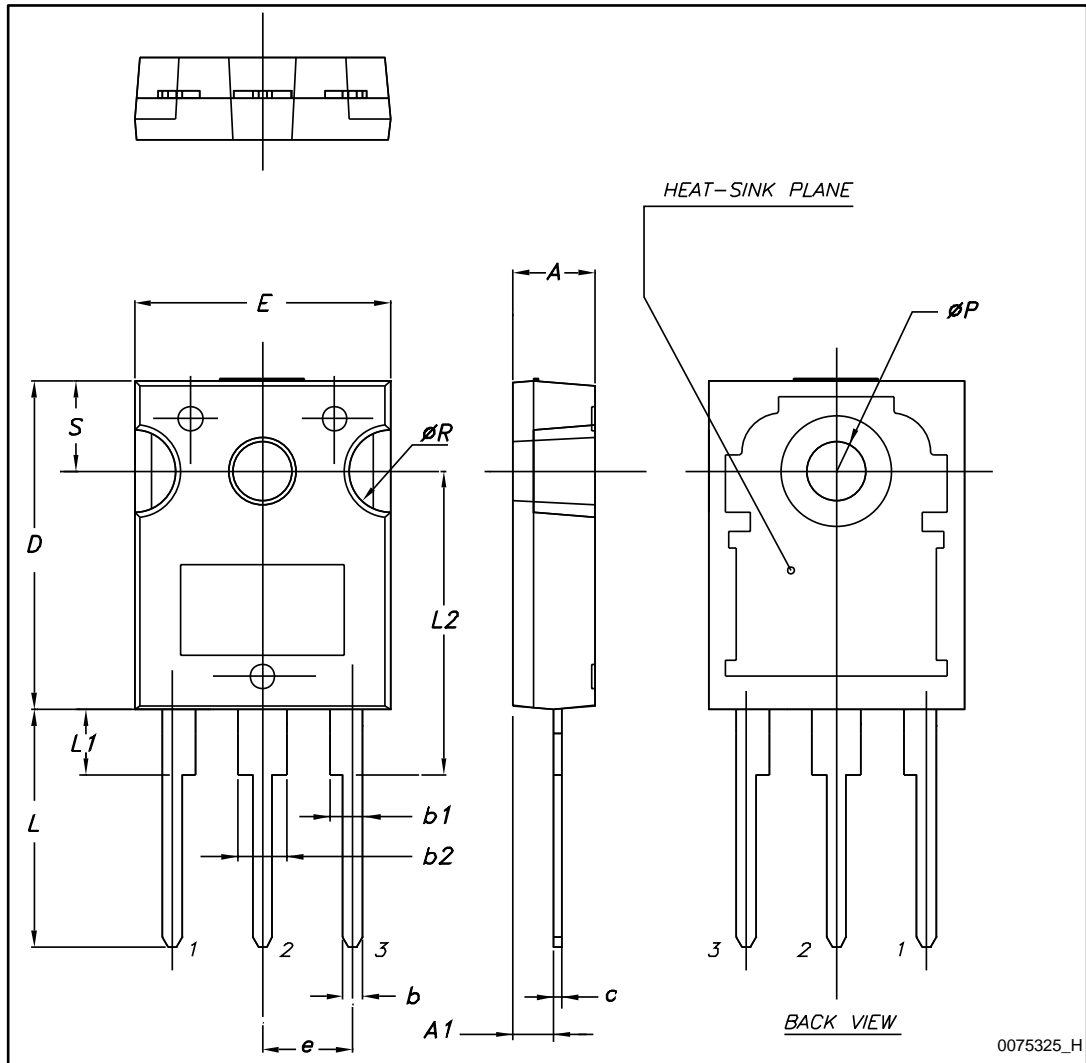


Table 9: TO-247 mechanical data

Dim.	mm.		
	Min.	Typ.	Max.
A	4.85		5.15
A1	2.20		2.60
b	1.0		1.40
b1	2.0		2.40
b2	3.0		3.40
c	0.40		0.80
D	19.85		20.15
E	15.45		15.75
e	5.30	5.45	5.60
L	14.20		14.80
L1	3.70		4.30
L2		18.50	
ØP	3.55		3.65
ØR	4.50		5.50
S	5.30	5.50	5.70

## 5 Revision history

Table 10: Document revision history

Date	Revision	Changes
01-Apr-2015	1	First release.
21-May-2015	2	Text edits throughout document In Section 2.1 Electrical characteristics (curves): - updated Figure 4: Output characteristics - updated Figure 5: Transfer characteristics

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